TEMIC

TV-Tuner-IC with Three Separate Oscillators and Mixers, SAW Driver, L.O.-Output and Tri-State-Band Switch

Features:

- 9 V supply voltage
- Frequency range from 48 to 860 MHz
- Band A: balanced high impedance mixer input and amplitude controlled oscillator
- Band B + C: balanced low impedance mixer input and symmetrical oscillator
- Balanced L.O.-output for prescalers or PLL

- SAW filter driver with low impedance output
- Voltage regulator for stable operating characteristics
- ESD protection on all pins except oscillator pins and RF-inputs

Package: SSO28

Block Diagram

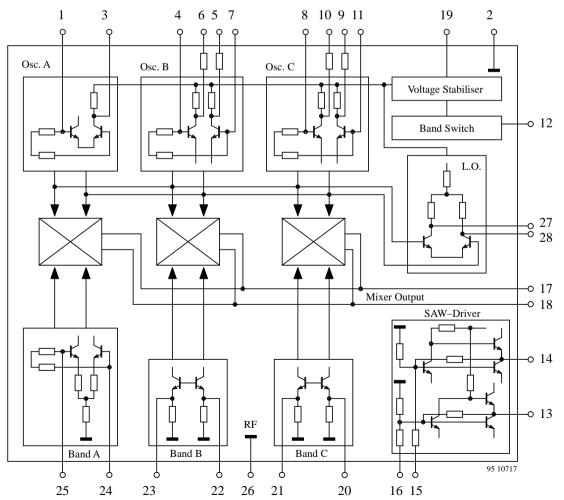


Figure 1. Block diagram pinning of U2309B

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Pin Configuration

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Osc A, base	1	<u> </u>	28	L.O. out
GND (common)	2	<u>'</u>	27	L.O. out
Osc A, coll.	3		26	GND (RF)
Osc B, base	4		25	RF in, A
Osc B, coll.	5		24	RF in, A
Osc B, coll.	6		23	RF in, B
Osc B, base.	7		22	RF in, B
Osc C, base	8	2	21	RF in, C
Osc C, coll.	9		20	RF in, C
Osc C, coll.	10	1	19	V_S
Osc C, base	11	1	18	Mix out
Band sw.	12	1	17	Mix out
SAWF, out.	13	1	16	SAWF, inp.
SAWF, out.	14	95 10720	15	SAWF, inp.

Pin	Cumbal	Function
	Symbol	
1	Osc A,base	Oscillator Band A, base
2	GND	Ground, common
	(common)	
3	Osc A, coll.	Oscillator band A, collector
4,7	Osc B, base	Oscillator band B, bases
5,6	Osc B, coll	Oscillator band B, collectors
8,11	Osc C, base	Oscillator band C, bases
9,10	Osc C, coll.	Oscillator band C, collectors
12	Band sw.	Tri – state band switch
13,14	SAWF, out.	SAW filter driver outputs
15,16	SAWF, inp.	SAW filter driver inputs
17,18	Mix out	Mixer outputs, open collector
19	V_{S}	Supply voltage Vs
20,21	RF in, C	RF inputs, band C
22,23	RF in, B	RF inputs, band B
24,25	RF in, A	RF inputs, band A
26	GND (RF)	Ground, RF part
27,28	L.O. out	L.O. outputs

Absolute Maximum Ratings

All voltages are referred to GND, Pin 2

Parameters		Symbol	Min.	Тур.	Max.	Unit
Supply voltage	Pin 19	Vs			10.5	V
RF inputs	Pin 20–25				5.0	V
IF outputs	Pin 17-18				10.5	V
Tri – state switch voltage	Pin 12	ViTRI			10.5	V
Junction temperature		Tj			150	С
Storage temperature		Tstg	-40		150	С

Operating Range

All voltages are referred to GND, Pin 2

Parameters	Test Conditions / Pins	Symbol	Min.	Тур.	Max.	Unit
Supply voltage	Pins 17–19	Vs	8,1	9,0	9,9	V
Ambient temperature		Tamb	-25		75	C
Thermal resistance	SSO-28	Rthja		128		K/W

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Electrical Characteristics

Test Conditions (unless otherwise specified) : $Vs = 9 \ V$. Tamb = 25 C. Reference point Pin 2 (Pin 26). Pin numbers in brackets for the mirrored version. Referred to test circuit page 6.

Parameters	Test Conditions / Pins	Symbol	Min.	Тур.	Max.	Unit
Supply voltage	Pins 17–19	Vs	8.1	9.0	9.9	V
Supply current	Pins 17–19	Is		42	50	mA
Band switch						
Voltage Band A	Pin 12	VSWA	0	0	1.0	V
Voltage Band B	Pin 12	VSWB	1.6	2.0	2.4	V
Voltage Band C	Pin 12	VSWC	3.4	4.0	5.0	V
Switching current	VSW = 5 V12	ISW			100	uA
L.O. – Output						
L. O. Level each output	RL = 50 Ohm27,28	PLO	-25		-17	dBm
SAW filter driver	fi = 36 MHz					
Input impedance	Pins 15,16	ZiSAW		450		Ohm
Output impedance	Pins 13,14	ZoSAW		70		Ohm
Voltage gain	Pins 15,16 13,14	GvSAW		17		dB
Band A						
Input frequency range	Pin 24	fiA	48		170	MHz
Input impedance	Figure 3. Pin 24	S11A				
Gain (note 4)	I/P to O/P	GA		28		dB
Noise figure DSB (note 2)	fiA = 50 MHz	NF		11,5		dB
_	fiA = 150 MHzI/P to O/P			12		dB
Input level for (note 3)	Each carrier					
IM3 (Interm. of 3rd order)	fiA = 71 MHzI/P	ViA		- 3		dBm
IM2 (Interm. of 2nd order)	fiA = 71 MHzI/P	ViA		-22		dBm
Band B (note 1)						
Input frequency range	Pins 22,23	fiB	170		470	MHz
Input impedance	Figure 3. Pins 22,23	S11B				
Gain (note 4)	I/P to O/P	GB		32		dB
Noise figure DSB (note 2)	fiB = 200 MHz	NF		9,5		dB
	fiB = 450 MHzI/P to O/P			10		dB
Input level for (note 3)	Each carrier					
IM3 (Interm. of 3rd order)	fiA = 300 MHzI/P	ViB		-28		dBm
Band C (note 1)						
Input frequency range	Pins 20,21	fiC	470		860	MHz
Input impedance	Figure 3, Pins.20,21	S11C				
Gain	I/P to O/P	GC		32		dB
Noise figure DSB (note 2)	fiB = 500 MHz	NF		10,5		dB
	fiB = 800 MHzI/P to O/P			11,5		dB
Input level for (note 3):	Each carrier					
IM3 (Interm. of 3rd order)	fiA = 600 MHzI/P	ViC		-28		dBm

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Notes

- 1) The RF inputs B and C are symmetrical driven by means of a hybrid for 180 phase shifting, consequently the source impedance is 100 Ohm. All other impedance for RF tests is 50 Ω .
- 2) The noise figure (NF) is the value for double–side–band measurement.
- 3) The intermodulation test (2-carrier-method) which is made on IF-centre is in reference to a signal-to-IM ratio of 60 dB
- 4) Gain is the ratio of the voltage at the primary coil of L5 to the available voltage at the input.

Application Circuit

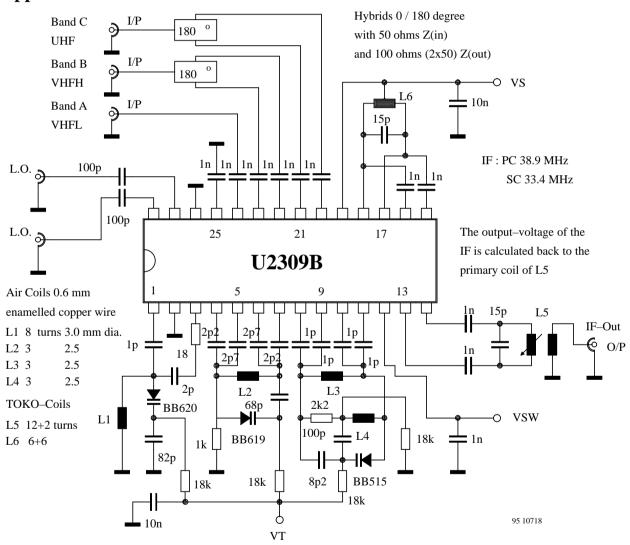


Figure 2. Test and principle application circuit

Note: All component values must be determined application specific. For more detailed information pls. request the application note

"Semiconductors for TV-Tuners and The New EasyLink Concept"

PCB for the R_{thJA} -Measurement

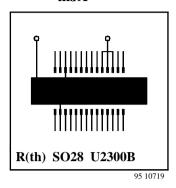


Figure 3. Figure 2: PCB for the Rthja – measurement:

35 um one-sided Cu-Coated epoxy PCB 40 x 40 x 1.5 mm

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Input Impedance Mixer Band A (S11A), Band C (S11B/C)

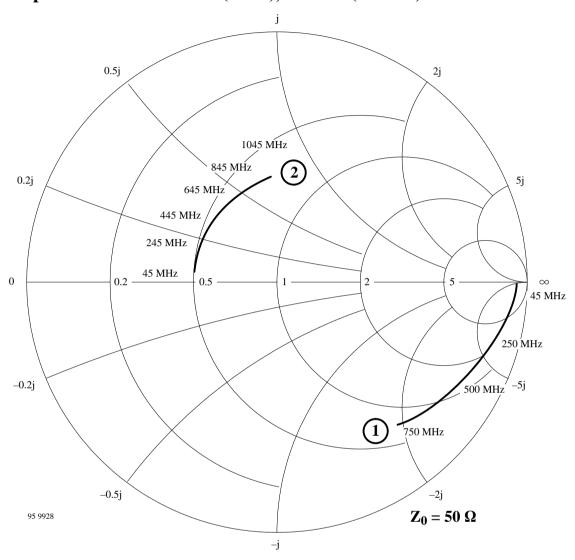


Figure 4. INPUT IMPEDANCE MIXER BAND A (S11A), B AND C (S11B/C)

1) VHF – Low Normalised to 50 Ohm, measuring range 45 MHz to 750 MHz.

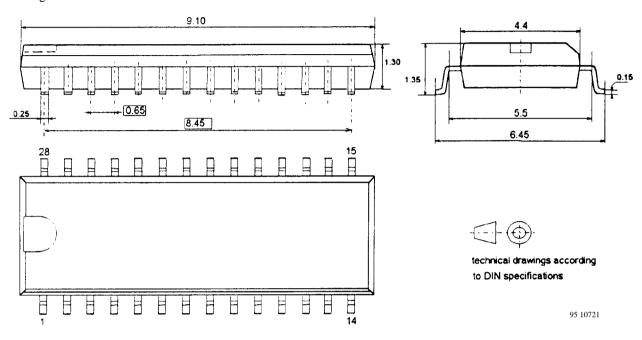
2) VHF – High and UHF

Normalised to 50 Ω , measuring range 45 MHz to 1045 MHz. Both inputs are driven symmetrical. The output impedance of the hybrid is 100 Ω , the measured levels are then calculated in reference to 50 Ω .

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Dimensions in mm:

Package: SSO28



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Ozone Depleting Substances Policy Statement

It is the policy of TEMIC TELEFUNKEN microelectronic GmbH to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice. Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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